PROMEX INDUSTRIES, INC. **JOB DESCRIPTION - NON-EXEMPT**

Position Title:	Die Attach Technician			**Position # or Level :**	1-4
Department:	Operations		**Reports to:**	Production Supervisor	
Employment Status:	Full Time	**Pay Grade or salary range:**	(List the pay grade or salary range for this position)	**% Travel Required**	NA

Position Summary: The Die Attach Technician is responsible for performing semiconductor die attach operations, including die bonding, placement, alignment, and attachment of semiconductor chips onto lead frames, substrates, or packages using epoxy, solder, or other die attach materials.

Essential Duties:

- Operate automatic die attach machines for semiconductor and chip on board assembly.
- Perform die attach processes using epoxy, silver-filled epoxy, solder, or other approved bonding materials.
- Set up and adjust die attach machine parameters.
- Perform first-piece inspection and verify die placement before mass production.
- Monitor and control epoxy dispensing to ensure proper coverage and consistency.
- Inspect die attach quality for defects.
- Perform routine machine cleaning, preventive maintenance, and basic troubleshooting.
- Conduct visual inspections using microscopes and other inspection equipment.
- Perform or assist with die shear testing to verify die bonding strength.
- Maintain accurate production records, machine settings, and inspection results.
- Follow standard operating procedures (SOPs), ESD requirements, and cleanroom guidelines.
- Work closely with process engineers, equipment technicians, and quality engineers to resolve production issues.

Other Duties & Responsibilities (Optional)

- N/A

Minimum Qualifications: H.S. Diploma or equivalent. Must be able to read and write English. Must be able to work with under a microscope.

1–3 years in semiconductor or microelectronics assembly, specifically in die attach, wire bond, or hybrid module assembly.

Key Competencies:

- Die attach machine operation and setup.
- Epoxy dispensing and material handling.
- Microscope inspection.
- Die attach defect identification.
- Machine parameter adjustment.
- Preventive maintenance and troubleshooting.
- ESD handling and cleanroom practices.

Preferred Skills:

- Prior experience with Besi Datacon multi-chip die bonder.

Position Title:	Die Attach Technician			**Position # or Level :**	1-4
Department:	Operations		**Reports to:**	Production Supervisor	
Employment Status:	Full Time	**Pay Grade or salary range:**	(List the pay grade or salary range for this position)	**% Travel Required**	NA

Work Environment: Indoors, environmentally controlled. Wear common ESD and protective equipment as necessary (i.e. safety glasses, gloves). While performing the duties of the job, the employee is regularly required to sit, stand and/or walk for extended periods of time; use hands and fingers; reach with hands and arms; and talk and hear. Specific vision abilities required by this job include close vision, color vision, peripheral vision, depth perception, and the ability to adjust focus.

Approvals Include required signatures here.

Name	**Title**	**Date**
Name	**Title**	**Date**